DB3X314J

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4Y

■ Basic Part Number

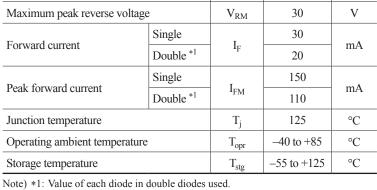
Dual DB2J314 (Common anode)

Packaging

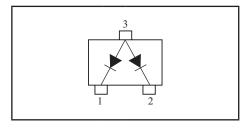
DB3X314J0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Reverse voltage		V _R	30	V	
Maximum peak reverse voltage		V_{RM}	30	V	
Forward current	Single	T	30	mA	
	Double *1	$I_{\rm F}$	20		
Peak forward current	Single	т.	150	mA	
	Double *1	I_{FM}	110		
Junction temperature		T _j	125	°C	
Operating ambient temperature		T _{opr}	-40 to +85	°C	
Storage temperature		T _{stg}	-55 to +125	°C	



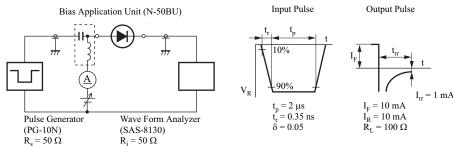
Unit: mm 2.9 0.4 0.16 2 (0.95) (0.95) 1.9 1: Cathode-1 3: Anode-1 2: Cathode-2 Anode-2 Mini3-G3-B Panasonic **JEITA** SC-59A TO-236AA/SOT-23 Code

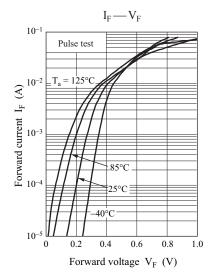


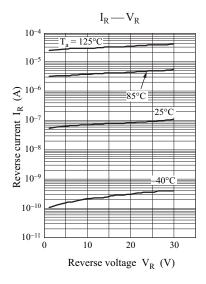
■ Electrical Characteristics $T_a = 25$ °C±3°C

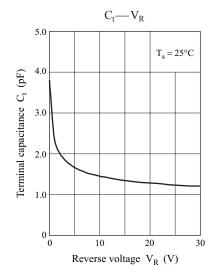
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 2 GHz
 - *1: t_{rr} measurement circuit









Ver. CED 2

Mini3-G3-B

1

(0.95)

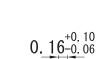
2. 90⁺⁰. 20 0. 40⁺⁰. 10 0. 40⁻⁰. 05 3

2. 90⁺⁰. 20 3

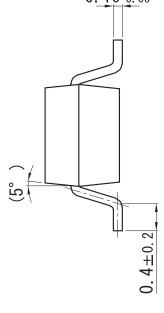
8. 0⁺⁰. 20

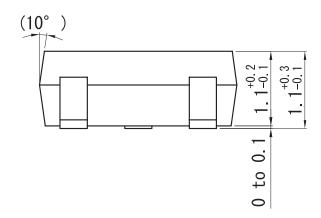
2

(0.65)



Unit: mm

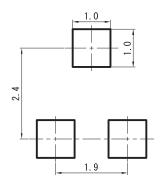




(0.95)

 1.9 ± 0.1

■ Land Pattern (Reference) (Unit: mm)



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